

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claim 1 (original): A method to assemble a pre-curved bolster plate to one side of a substrate having a first side and a second side, comprising:

attaching a component to an electrical contact area on said first side of said substrate; and

attaching said pre-curved bolster plate on said second side of said substrate, wherein said pre-curved bolster plate is attached to said second side opposite said electrical contact area on said first side of said substrate.

Claim 2 (original): The method of claim 1, wherein said component is a land grid array (LGA) component.

Claim 3 (original): The method of claim 1, wherein said substrate is selected from a group of substrates consisting of: a printed circuit board (PCB), a multi-chip module (MCM), and a flexible substrate.

Claim 4 (original): The method of claim 1, wherein said pre-curved bolster plate includes a material selected from the group consisting of: a stainless steel alloy, a powder-coated spring steel alloy, a plated spring steel alloy, a painted spring steel alloy, a titanium steel alloy, a

carbon steel alloy, a magnesium alloy, and an aluminum alloy.

Claim 5 (original): The method of claim 1, wherein said pre-curved bolster plate has a spherical curvature.

Claim 6 (original): The method of claim 1, wherein said pre-curved bolster plate has a cylindrical curvature.

Claim 7 (original): The method of claim 1, wherein said pre-curved bolster plate has a radius of curvature in excess of 100 inches (254 centimeters).

Claims 8-12 (previously cancelled)

Claims 13-20 (previously cancelled)

Claim 21 (previously presented): A method for providing support to a substrate, the method comprising:

attaching a component to an electrical contact area on a first side of the substrate; and

attaching a pre-curved bolster plate on a second side of the substrate, the pre-curved bolster plate having a pre-calculated radius of curvature prior to attachment to the second side of the substrate.

Claim 22 (previously presented): The method of claim 21, wherein the component comprises a land grid array (LGA) component.

Claim 23 (previously presented): The method of claim 21, wherein the substrate is selected from a group of substrates consisting of: a printed circuit board (PCB), a multi-chip module (MCM), and a flexible substrate.

Claim 24 (previously presented): The method of claim 21, wherein the pre-curved bolster plate includes a material selected from a group consisting of: a stainless steel alloy, a powder-coated spring steel alloy, a plated spring steel alloy, a painted spring steel alloy, a titanium steel alloy, a carbon steel alloy, a magnesium alloy, and an aluminum alloy.

Claim 25 (previously presented): The method of claim 21, wherein the pre-curved bolster plate has a spherical curvature.

Claim 26 (previously presented): The method of claim 21, wherein the pre-curved bolster plate has a cylindrical curvature.

Claim 27 (previously presented): The method of claim 21, wherein the pre-curved bolster plate has a radius of curvature in excess of approximately 100 inches (254 centimeters).

Claim 28 (previously presented): A substrate support assembly produced in accordance with the method of claim 21.

Claims 29-36 (previously cancelled)

Claim 37 (previously presented): A method for coupling a plate member to an electrical packaging assembly, the method comprising:

- providing an electrical packaging assembly;
- providing a plate member that is pre-curved;
- disposing the plate member against the electrical packaging assembly;
- flexing the plate member towards the electrical packaging assembly to produce a flexed plate member; and
- coupling the flexed plate member to the electrical packaging assembly.

Claim 38 (previously presented): The method of Claim 37 wherein said flexing comprises curving opposed ends of the plate member towards a substrate of the electrical packaging assembly.

Claim 39 (previously presented): The method of Claim 37 wherein said flexing comprises curving opposed ends of the plate member towards a substrate of the electrical packaging assembly until the plate member is generally flushed against the substrate.

Claim 40 (previously presented): The method of Claim 37 wherein said electrical packaging assembly comprises an electrical component having a plurality of leads attached to an electrical contact area of a substrate.

Claim 41 (previously presented): The method of Claim 39 wherein said electrical packaging assembly comprises an electrical component having a plurality of leads attached to an electrical contact area of said substrate.

Claim 42 (previously presented): The method of Claim 37 wherein said plate member is stamped to achieve a spherical curvature.

Claim 43 (previously presented): The method of Claim 41 wherein said plate member is stamped to achieve a cylindrical curvature.

Claim 44 (previously presented): The method of Claim 37, wherein said plate member is fabricated from a material selected from the group of materials consisting of: a stainless steel alloy, a powder-coated spring steel alloy, a plated spring steel alloy, a painted spring steel alloy, a titanium steel alloy, a carbon steel alloy, a magnesium alloy, and an aluminum alloy.

Claim 45 (previously presented): The method of Claim 43, wherein said plate member is fabricated from a material selected from the group of materials consisting of: a stainless steel alloy, a powder-coated spring steel alloy, a plated spring steel alloy, a painted spring steel alloy, a titanium steel alloy, a carbon steel alloy, a magnesium alloy, and an aluminum alloy.

Claim 46 (previously presented): A method for assembling a bolster plate to a circuit member, the method comprising:

providing a circuit member;

disposing a curved bolster plate against the circuit member;

curving the bolster plate towards the circuit member to change the curved bolster plate into a flat bolster plate; and

coupling the flat bolster plate to the circuit member.

Claim 47 (previously presented): The method of Claim 46 wherein said curving comprises curving opposed ends of the bolster plate towards the circuit member.

Claim 48 (previously presented): The method of Claim 46 wherein said curving comprises curving opposed ends of the bolster plate towards the circuit member until the bolster plate is generally flushed against the circuit member.

Claim 49 (previously presented): The method of Claim 46 wherein said circuit member includes an electrical contact area having a plurality of leads attached thereto.

Claim 50 (previously presented): The method of Claim 48 wherein said circuit member includes an electrical contact area having a plurality of leads attached thereto.

Claim 51 (previously presented): The method of Claim 46 wherein said bolster plate is stamped to achieve a spherical curvature.

Claim 52 (previously presented): The method of Claim 50 wherein said bolster plate is stamped to achieve a cylindrical curvature.

Claim 53 (previously presented): The method of Claim 46, wherein said bolster plate is fabricated from a material selected from the group of materials consisting of: a stainless steel alloy, a powder-coated spring steel alloy, a plated spring steel alloy, a painted spring steel alloy, a titanium steel alloy, a carbon steel alloy, a magnesium alloy, and an aluminum alloy.

Claim 54 (previously presented): The method of Claim 52, wherein said bolster plate is fabricated from a material selected from the group of materials consisting of: a stainless steel alloy, a powder-coated spring steel alloy, a plated spring steel alloy, a painted spring steel alloy, a titanium steel alloy, a carbon steel alloy, a magnesium alloy, and an aluminum alloy.

Claim 55 (previously presented): An assembly produced in accordance with the method of claim 46.

Claim 56 (previously presented): The method of claim 1, wherein the pre-curved bolster plate has a radius of curvature.

Claim 57 (previously presented): The method of claim 56, wherein the radius of curvature is pre-calculated.

Claim 58 (previously presented): The method of claim 57, wherein the radius of curvature is pre-calculated such that the pre-curved bolster plate deflects into a flat plate after a clamping force is applied to the component which is assembled on the substrate and to the pre-curved bolster plate which is assembled on the substrate.

Claim 59 (previously presented): The method of claim 1, wherein the pre-curved bolster plate has an entire surface that is in contact with the substrate when a clamping force is applied to the pre-curved bolster plate and to the substrate.

Claim 60 (previously presented): The method of claim 1, further comprising:

clamping the component and the bolster plate to the substrate.

Claim 61 (previously presented): The method of claim 1, further comprising:

clamping the component and the bolster plate to the substrate by use of a clamp.

Claim 62 (previously presented): The method of claim 1, further comprising:

clamping the component and the bolster plate to the substrate by bolting a clamp to the substrate.

Claim 63 (previously presented): The method of claim 1, further comprising:

clamping the component to the substrate by bolting a clamp to the substrate by use of a bolt and a spring.

Claim 64 (previously presented): An assembly produced in accordance with the method of claim 1.

Claim 65 (previously presented): The method of claim 21, wherein the radius of curvature is pre-calculated such that the pre-curved bolster plate deflects into a flat plate after a clamping force is applied to the component which is assembled on the substrate and to the pre-curved bolster plate which is assembled on the substrate.

Claim 66 (previously presented): The method of claim 37, wherein the plate member has a radius of curvature.

Claim 67 (previously presented): The method of claim 66, wherein the radius of curvature is pre-calculated.

Claim 68 (previously presented): The method of claim 67, wherein the radius of curvature is pre-calculated such that the plate member deflects into the flat plate member after a clamping force is applied to the electrical packaging assembly and to the plate member which is assembled on the electrical packaging assembly.

Claim 69 (previously presented): The method of claim 46, wherein the curved bolster plate has a radius of curvature.

Claim 70 (previously presented): The method of claim 69, wherein the radius of curvature is pre-calculated.

Claim 71 (previously presented): The method of claim 70, wherein the radius of curvature is pre-calculated such that the curved bolster plate deflects into the flat bolster plate after a clamping force is applied to the circuit member and to the curved bolster plate which is assembled on the circuit member.

Claim 72 (previously presented): The method of claim 46, wherein the curved bolster plate has an entire surface that is in contact with the circuit member when a clamping force is applied to the curved bolster plate and to the circuit member.

Claim 73 (previously presented): The method of claim 46, wherein coupling the flat bolster plate comprises:

clamping a component and the bolster plate to the circuit member.

Claim 74 (previously presented): The method of claim 46, wherein coupling the flat bolster plate comprises:

clamping a component and the bolster plate to the circuit member by use of a clamp.

Claim 75 (previously presented): The method of claim 46, wherein coupling the flat bolster plate comprises:

clamping a component and the bolster plate to the circuit member by bolting a clamp to the circuit member.

Claim 76 (previously presented): The method of claim 46, wherein coupling the flat bolster plate comprises:

clamping a component to the circuit member by bolting a clamp to the circuit member by use of a bolt and a spring.